

RJK5014DPK-VB Datasheet

N-Channel 600 V (D-S) Super Junction Power MOSFET

PRODUCT SUMMARY					
V _{DS} (V)	600				
R _{DS(on)} at 25 °C (Ω)	$V_{GS} = 10 V$	0.23			
Q _g Typ. (nC)	24				
Q _{gs} (nC)	6				
Q _{gd} (nC)	11				
Configuration	Single				

FEATURES

- Low figure-of-merit (FOM) $\rm R_{on}~x~Q_{g}$
- Low input capacitance (C_{iss})
- Reduced switching and conduction losses
- Ultra low gate charge (Q_q)
- Avalanche energy rated (UIS)



TO-3P G D S D (TAB) N-Channel MOSFET

APPLICATIONS

- Server and telecom power supplies
- Switch mode power supplies (SMPS)
- Power factor correction power supplies (PFC)
- Lighting
 - High-intensity discharge (HID)
 - Fluorescent ballast lighting
- Industrial
 - Welding
 - Induction heating
 - Motor drives
 - Battery chargers
 - Renewable energy
 - Solar (PV inverters)

ABSOLUTE MAXIMUM RATINGS ($T_C = 25 \text{ °C}$, unless otherwise noted)								
PARAMETER			SYMBOL	LIMIT	UNIT			
Drain-Source Voltage			V _{DS}	600	v			
Gate-Source Voltage			V _{GS}	± 30	V			
Continuous Drain Current (T _J = 150 °C)	V at 10 V	T _C = 25 °C	- I _D	15				
	V _{GS} at 10 V	$T_{\rm C} = 25 ^{\circ}{\rm C}$ $T_{\rm C} = 100 ^{\circ}{\rm C}$		10	А			
Pulsed Drain Current ^a			I _{DM}	45				
Linear Derating Factor				1.4	W/°C			
Single Pulse Avalanche Energy ^b			E _{AS}	286	mJ			
Maximum Power Dissipation			PD	180 V				
Operating Junction and Storage Temperature Range			T _J , T _{stg}	-55 to +150	°C			
Drain-Source Voltage Slope	T _J = 125 °C		al) / / alt	37				
Reverse Diode dV/dt d		dV/dt	23	V/ns				
Soldering Recommendations (Peak Temperature) ^c	for 10 s			300	°C			

Notes

a. Repetitive rating; pulse width limited by maximum junction temperature.

b. $V_{DD} = 50$ V, starting $T_J = 25$ °C, L = 28.2 mH, $R_g = 25 \Omega$, $I_{AS} = 4.5$ A.

c. 1.6 mm from case.

d. $I_{SD} \leq I_D, \, dI/dt = 100$ A/µs, starting $T_J = 25 \ ^\circ C.$



THERMAL RESISTANCE RATI	NGS								
PARAMETER	SYMBOL	TYP. MAX.			UNIT				
Maximum Junction-to-Ambient	R _{thJA}	- 62							
Maximum Junction-to-Case (Drain)	R _{thJC}	- 0.7				°C/W			
SPECIFICATIONS (T _J = 25 $^{\circ}$ C, u	nless otherwi	se noted)							
PARAMETER	SYMBOL	TES	T CONDIT	IONS	MIN.	TYP.	MAX.	UNIT	
Static		•							
Drain-Source Breakdown Voltage	V _{DS}	V _{GS} =	= 0 V, I _D =	250 µA	600	-	-		
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	Reference	e to 25 °C,	I _D = 1 mA	-	0.75	-	V/°C	
Gate-Source Threshold Voltage (N)	V _{GS(th)}	V _{DS} =	= V _{GS} , I _D =	250 µA	2	-	4	V	
		$V_{GS} = \pm 20 V$ $V_{GS} = \pm 30 V$		-	-	± 100	nA		
Gate-Source Leakage	I _{GSS}			-	-	± 1	μA		
Zero Gate Voltage Drain Current		V _{DS} =	= 600 V, V _C	_{iS} = 0 V	-	-	1		
	I _{DSS}	V _{DS} = 520 V	$V_{DS} = 520 \text{ V}, V_{GS} = 0 \text{ V}, T_J = 125 \text{ °C}$			-	10	μA	
Drain-Source On-State Resistance	R _{DS(on)}	V _{GS} = 10 V		I _D = 8 A	-	0.23	-	Ω	
Forward Transconductance	g _{fs}	V _{DS}	= 30 V, I _D	= 8 A	-	5.6	-	S	
Dynamic					1	1	<u> </u>	1	
Input Capacitance	C _{iss}	$\label{eq:VGS} \begin{array}{c} V_{GS} = 0 \ V, \\ V_{DS} = 100 \ V, \\ f = 1 \ \text{MHz} \end{array}$		-	1640	-	pF		
Output Capacitance	Coss			-	80	-			
Reverse Transfer Capacitance	C _{rss}			-	4	-			
Effective Output Capacitance, Energy Related ^a	C _{o(er)}	$V_{DS} = 0$ V to 520 V, $V_{GS} = 0$ V		-	63	-			
Effective Output Capacitance, Time Related ^b	C _{o(tr)}			-	213	-			
Total Gate Charge	Qg	$V_{GS} = 10 V$ $I_D = 8 A, V_{DS}$			-	24	48	nC	
Gate-Source Charge	Q _{gs}			A, V _{DS} = 520 V	-	6	-		
Gate-Drain Charge	Q _{gd}				-	11	-		
Turn-On Delay Time	t _{d(on)}	V_{DD} = 520V, I $_D$ = 8 A, V_{GS} = 10 V, R_g = 9.1 Ω		-	18	36	ns		
Rise Time	t _r			-	24	48			
Turn-Off Delay Time	t _{d(off)}			-	48	96			
Fall Time	t _f			-	25	50			
Gate Input Resistance	Rg	f = 1 MHz, open drain		-	0.8	-	Ω		
Drain-Source Body Diode Characteristic	s	T				1		-	
Continuous Source-Drain Diode Current	I _S	MOSFET symbol showing the integral reverse p - n junction diode		-	-	15	A		
Pulsed Diode Forward Current	I _{SM}			-	-	38			
Diode Forward Voltage	V _{SD}	$T_{\rm J} = 25 \ ^{\circ}\text{C}, \ I_{\rm S} = 8 \text{ A}, \ V_{\rm GS} = 0 \text{ V}$		-	-	1.2	V		
Reverse Recovery Time	t _{rr}	$T_J = 25 \text{ °C}, I_F = I_S = 8 \text{ A},$ dl/dt = 100 A/µs, V _R = 400 V		-	325	-	ns		
Reverse Recovery Charge	Q _{rr}			-	4.6	-	μC		
Reverse Recovery Current	I _{RRM}			_	20	_	A		

Notes

a. $C_{oss(er)}$ is a fixed capacitance that gives the same energy as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DSS} . b. $C_{oss(tr)}$ is a fixed capacitance that gives the same charging time as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DSS} .



TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

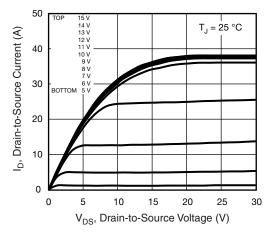


Fig. 1 - Typical Output Characteristics

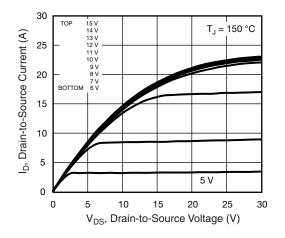


Fig. 2 - Typical Output Characteristics

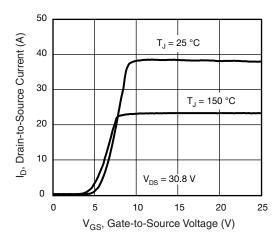


Fig. 3 - Typical Transfer Characteristics

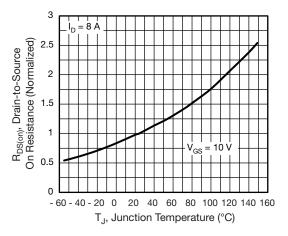


Fig. 4 - Normalized On-Resistance vs. Temperature

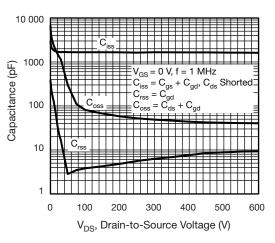


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

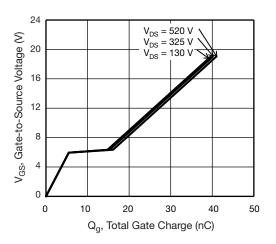


Fig. 6 - Typical Gate Charge vs. Gate-to-Source Voltage

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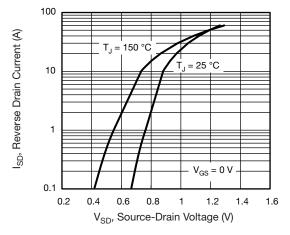


Fig. 7 - Typical Source-Drain Diode Forward Voltage

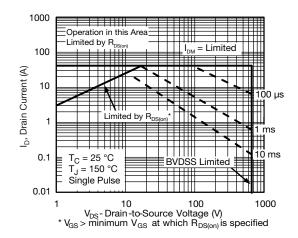


Fig. 8 - Maximum Safe Operating Area

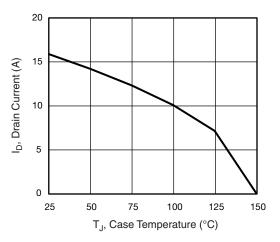


Fig. 9 - Maximum Drain Current vs. Case Temperature

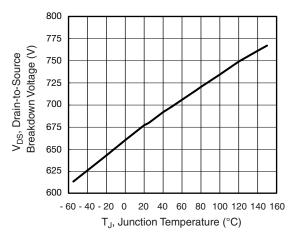


Fig. 10 - Temperature vs. Drain-to-Source Voltage

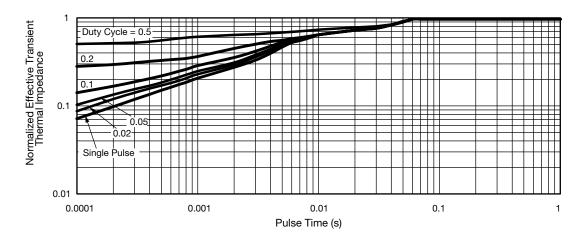


Fig. 11 - Normalized Thermal Transient Impedance, Junction-to-Case



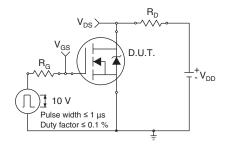


Fig. 12 - Switching Time Test Circuit

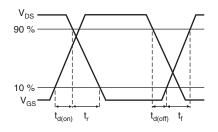


Fig. 13 - Switching Time Waveforms

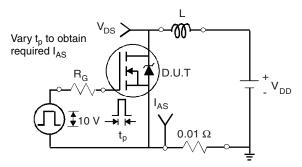


Fig. 14 - Unclamped Inductive Test Circuit

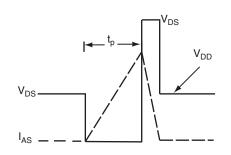


Fig. 15 - Unclamped Inductive Waveforms

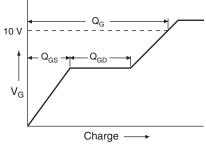


Fig. 16 - Basic Gate Charge Waveform

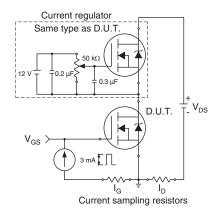
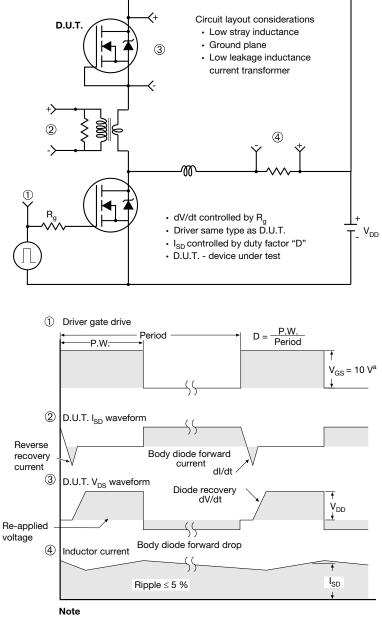


Fig. 17 - Gate Charge Test Circuit



Peak Diode Recovery dV/dt Test Circuit

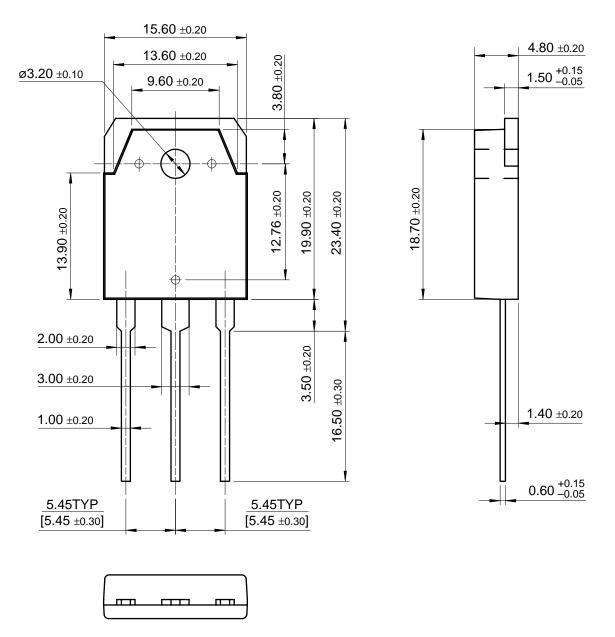


a. $V_{GS} = 5$ V for logic level devices

Fig. 18 - For N-Channel



TO-3P





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